

Amendments To Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-6 (Cancelled)

7. (Withdrawn) A substrate cutting system according to claim 6, wherein the substrate supporting section is a plurality of cylindrical rollers.

8. (Withdrawn) A substrate cutting system according to claim 7, comprising at least one rotation transmission means for rotating the plurality of cylindrical rollers in accordance with the movement of the scribing device guide body.

9. (Withdrawn) A substrate cutting system according to claim 7, comprising a control section for rotating the plurality of cylindrical rollers in accordance with the movement of the scribing device guide body.

Claims 10-15 (Cancelled)

16. (Withdrawn) A substrate cutting system according to claim 15, wherein the substrate supporting section is a plurality of cylindrical rollers.

17. (Withdrawn) A substrate cutting system according to claim 16, comprising at least one rotation transmission means for rotating the plurality of cylindrical rollers in accordance with the movement of the scribing device guide body.

18. (Withdrawn) A substrate cutting system according to claim 16, comprising a control section for rotating the plurality of cylindrical rollers in accordance with the movement of the scribing device guide body.

Claim 19 – 59 (Cancelled)

60. (new) A substrate cutting system, comprising:
a pair of scribing line forming means arranged facing each other;

a pair of scribing devices for supporting the pair of scribing line forming means such that one of the pair of scribing line forming means moves on a first surface of a substrate in an X axis direction and the other of the pair of scribing forming means moves on a second surface of the substrate in the X axis direction;

a scribing device guide body for supporting the pair of scribing devices such that the pair of scribing devices moves in a Y axis direction; and

a substrate supporting means for supporting the substrate in an X-Y plane such that the pair of scribing line forming means scribes the first surface of the substrate and the second surface of the substrate.

wherein the substrate supporting means is placed in both sides of Y axis direction of the pair of scribing devices; and is configured to be relatively movable to the Y axis direction relative to the substrate, and wherein

the pair of scribing devices forms a scribing line by moving to the Y axis direction relative to the substrate in conjunction with the substrate supporting device.

61. (new) The substrate cutting system according to claim 60, wherein the substrate supporting means comprises;

a substrate supporting means supported in the scribing device guide body, wherein the substrate supporting means moves to the Y axis direction in conjunction with the pair of scribing devices; and

a fixing device for fixing the substrate in the X-Y plane.

62. (new) The substrate cutting system according to claim 60, wherein the substrate supporting means has a plurality of belts supporting the substrate.

63. (new) The substrate cutting system according to claim 62, comprising at least one rotation transmission means for circling the plurality of belts in accordance with the movement of the scribing device guide body.

64. (new) A substrate cutting system according to claim 62, wherein

the plurality of belts is wound around between a frame on a carry-in side of the substrate and a frame on a carry-out side of the substrate, and

the plurality of belts lowers below the scribing device guide body or emerges above the scribing device guide body from under the scribing device guide body while the first substrate supporting section is moving.

65. (new) A substrate cutting system according to claim 60, wherein the substrate is a mother substrate bonding to a pair of mother substrates.

66. (new) A substrate cutting method, comprising:

a pair of scribing line forming means arranged facing each other;

a pair of scribing devices for supporting the pair of scribing line forming means such that one of the pair of scribing line forming means moves on a first surface of a substrate in an X axis direction and the other of the pair of scribing line forming means moves on a second surface of the substrate in the X axis direction;

ascribing device guide body for supporting the pair of scribing devices such that the pair of scribing devices moves in a Y axis direction; and

a substrate supporting means for supporting the substrate in an X-Y plane such that the pair of scribing line forming means scribes the first surface of the substrate and the second surface of the substrate,

wherein in a substrate cutting system that the substrate supporting means is placed on both sides of Y axis direction of the pair of scribing device; and is configured to be relatively movable to Y axis direction relative to the substrate in conjunction with the pair of scribing devices, a method for cutting the substrate for

forming a scribing line by moving the pair of scribing devices to the Y axis direction relative to the substrate in conjunction with the substrate supporting device.

67. (new) A substrate cutting method according to claim 66, wherein

the substrate supporting means support the substrate so that the substrate supporting means does not movably contact with the substrate, and so that the substrate supporting means does not apply force to the substrate.